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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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# 2SA2161G

### Silicon PNP epitaxial planar type

For general amplification Complementary to 2SC6037G

#### ■ Features

- Low collector-emitter saturation voltage V<sub>CE(sat)</sub>
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	$V_{CBO}$	-15	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-12	V	
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	-5	V	
Collector current	$I_{C}$	-500	mA	
Peak collector current	$I_{CP}$	-1	A	
Collector power dissipation	P <sub>C</sub>	125	mW	
Junction temperature	$T_{j}$	125	°C	
Storage temperature	T <sub>stg</sub>	-55 to +125	°CO	

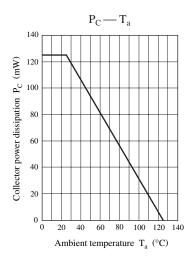
#### ■ Package

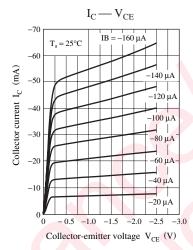
- Code SSMini3-F3
- Marking Symbol: 2U
- Pin Name
  - 1. Base
  - 2. Emitter
  - 3. Collector

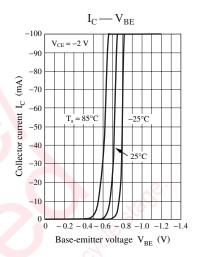
### ■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

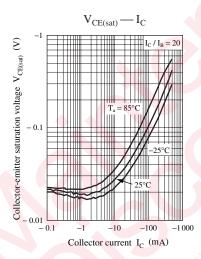
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{\rm C} = -10 \ \mu A, I_{\rm E} = 0$	-15			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = -1 \text{ mA}, I_{\rm B} = 0$	-12	25		V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = -10 \mu\text{A},  I_C = 0$	-5			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = -15 \text{ V}, I_E = 0$	7.9		- 0.1	μΑ
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = -2 \text{ V}, I_{C} = -10 \text{ mA}$	270		680	
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -200 \text{ mA}, I_B = -10 \text{ mA}$			-250	mV
Transition frequency	$f_T$	$V_{CB} = -2 \text{ V}, I_E = 10 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		4.5		pF
(Common base, input open circuited)		10.11				

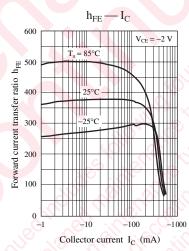
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

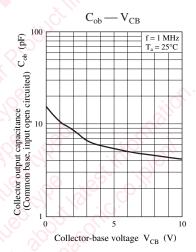




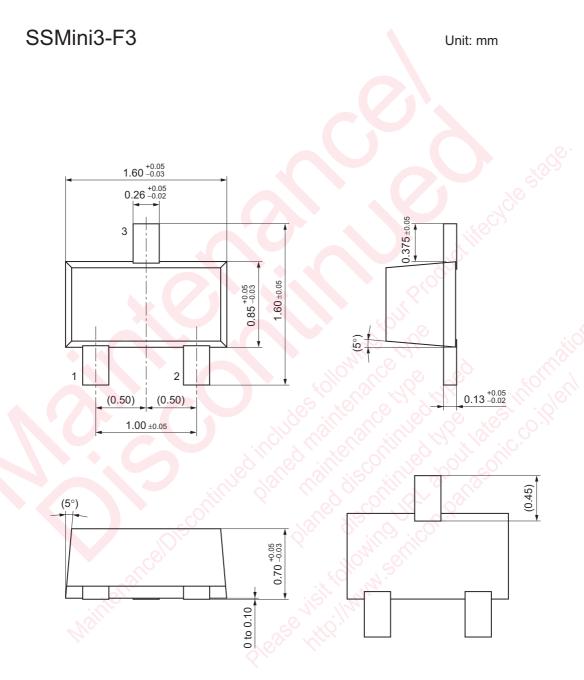








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